



REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE:

1. MATERIAL:

- 1.1 INSULATOR: LCP+30%GF, UL94 V-0.
- 1.2 CONTACT 1~4PIN: C5191-EH.
- 1.3 CONTACT 5~9PIN: C5191-EH.
- 1.4 SHELL: SUS304 3/4H

2. PLATING:

2.1 CONTACT:

CONTACT AREA: GOLD PLATING.
SOLDER AREA: 100u" Min MATTE TIN PLATING.
UNDER PLATE: 50u" Min NICKEL PLATING.

2.2 SHELL: 50u" Min. NICKEL PLATED OVERALL

3. CHARACTERISTICS:

3.1 ELECTRICAL CHARACTERISTICS;

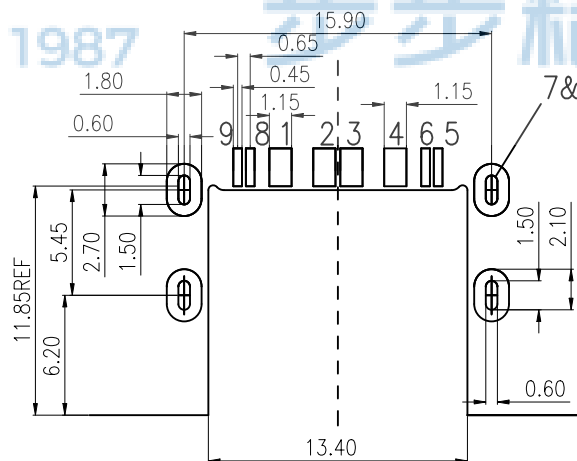
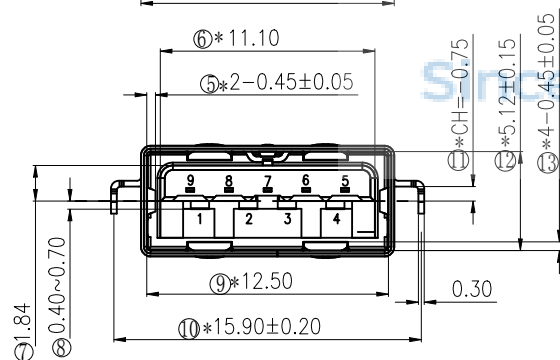
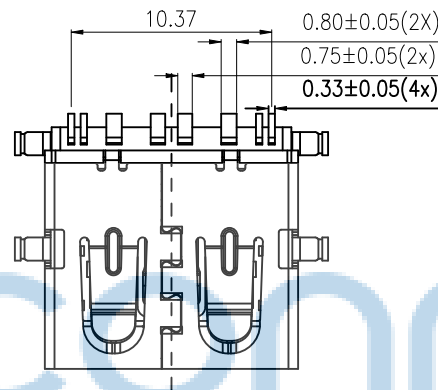
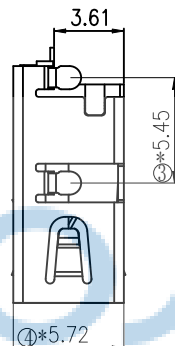
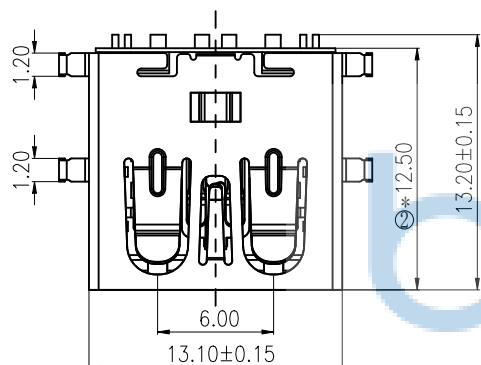
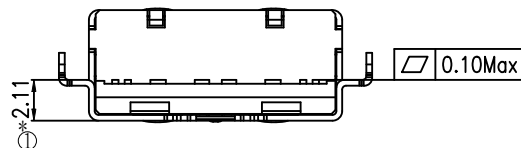
CONTACT RESISTANCE: 30mΩ MAXIMUM
CONTACT CURRENT RATING: 3A
DIELECTRIC WITHSTANDING VOLTAGE: 500 V R.M.S.
INSULATION RESISTANCE: 100 MEGOHMS MIN
OPERATING TEMPERATURE: -25°C ~ +85°C

3.2 MECHANICAL:

MATING FORCE: 8N-20N.
UNMATING FORCE: 8N-20N.

4. PART MUST COMPLY ROHS SPECIFICATION

5. WAVE SOLDER: THE CONNECTOR SHALL BE MOUNTED ON THE PCB. THE TEMPERATURE OF THE SOLDER SHALL BE 260±5 °C AND IMMERSION DURATION 5 SECONDS.



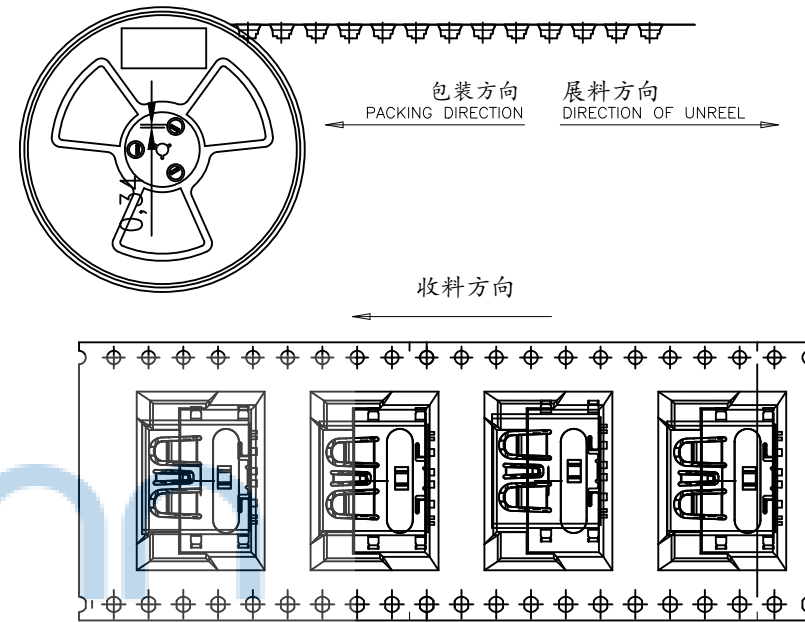
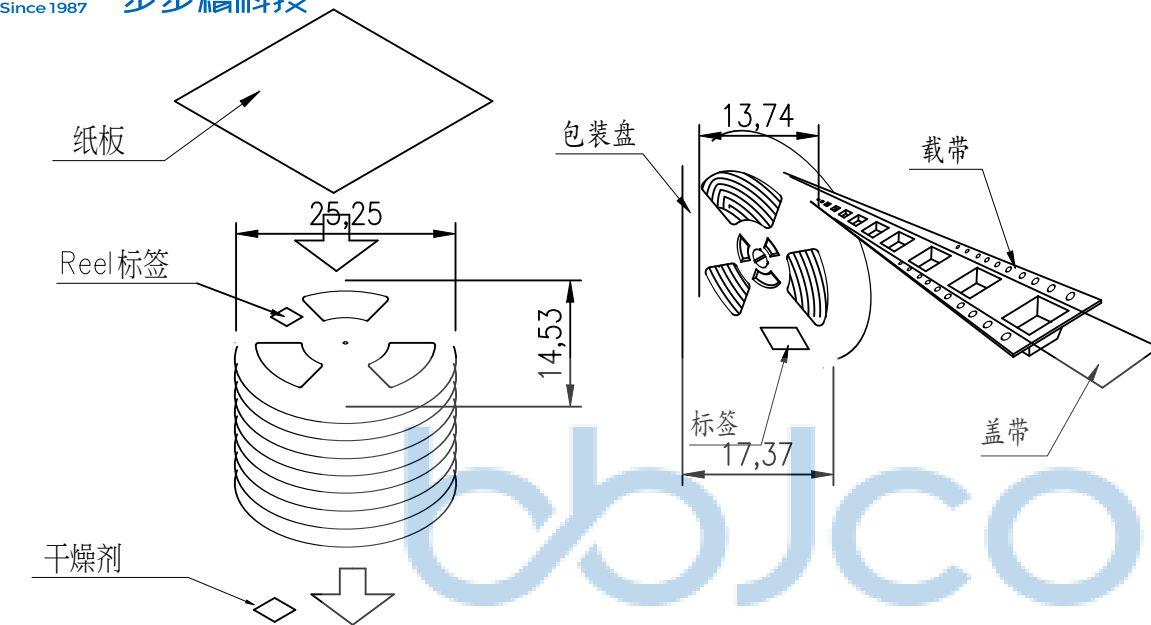
TOLERANCE: ±0.05, RECOMMENDED PCB LAYOUT (TOP VIEW)

Pin NUMBER	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield

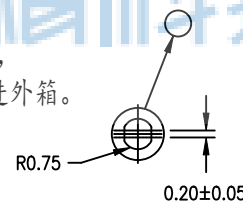
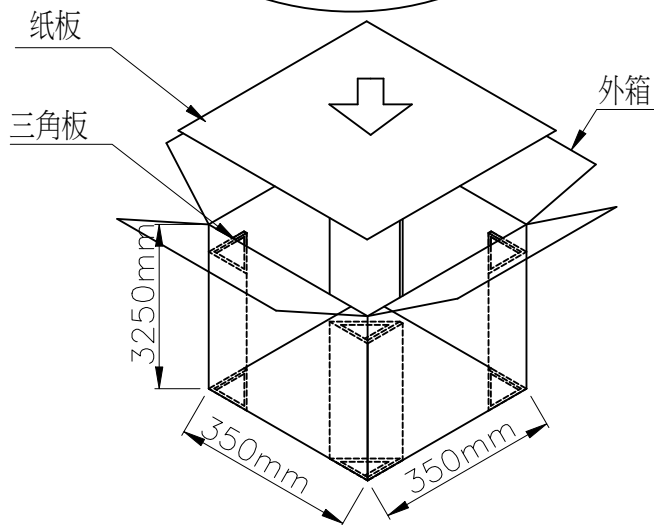
3	SHELL	SUS304-3/4H	50u" Min. NICKEL PLATED OVERALL
2	CONTACT	C5191-EH	GOLD PLATED G/F ON CONTACT AREA
1	HSG	LCP+30%GF	UL94V-0
NO. PART NAME		MATERIAL	DESCRIPTION
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PDWG. NO:		0536-1	
APPD.		JM_Zheng	
CHKD.		LYX	
DR.		TSP	
NAME:		USB 3.1 A母 10Gbps 沉板3.61 SMT 四脚插 平口 不锈钢外壳 LCP蓝胶 L=12.50	
PJ. NO.:		127-271-090005-P2G	
SIZE:		A4 DRW NO.:	
FINISH:		SEE NOTES	
MAT'L.:		SEE NOTES	
SCALE:		N/A	
REV.:		A0	
UNIT:		mm	
PAGE:		1/2	



深圳市步步精科技有限公司



1. 外箱底部先垫一片纸板。
2. 外箱四个内角加入三角板支撑
3. 把8卷封好的产品平放进防水袋，并放入2包干燥剂，再一起平放进外箱。
4. 注意REEL之标签一律朝上
5. 接上一工站，上层放一片纸板
6. 标签贴于纸箱外侧右上方



SCALE 2:1



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		NAME: USB 3.1 A母 10Gbps 沉板3.61 SMT 四脚插 平口 不锈钢外壳 LCP蓝胶 L=12.50	
X': ±3' .X': ±2' .XX': ±1'		PJ. NO.: 127-271-090005-P2G	
APPD. JM_Zheng		SIZE: A4 DRW NO.:	
CHKD. LYX		FINISH: SEE NOTES MAT'L.: SEE NOTES	
DR. TSP		SCALE: N/A REV.: A0 UNIT: mm PAGE: 2/2	
PDWG.NO: 0536-1			